



STGD5NB120SZ-1 STGD5NB120SZ

N-CHANNEL 5A - 1200V DPAK/IPAK INTERNALLY CLAMPED PowerMESH™ IGBT

Table 1: General Features

| TYPE | V _{CES} | V _{CE(sat)} | I _C |
|----------------|------------------|----------------------|----------------|
| STGD5NB120SZ | 1200 V | < 2.0 V | 5 A |
| STGD5NB120SZ-1 | 1200 V | < 2.0 V | 5 A |

- HIGH INPUT IMPEDANCE (VOLTAGE DRIVEN)
- LOW ON-VOLTAGE DROP (V_{cesat})
- HIGH CURRENT CAPABILITY
- OFF LOSSES INCLUDE TAIL CURRENT
- HIGH VOLTAGE CLAMPING FEATURES

DESCRIPTION

Using the latest high voltage technology based on a patented strip layout, STMicroelectronics has designed an advanced family of IGBTs, the PowerMESH™ IGBTs, with outstanding performances. The suffix "S" identifies a family optimized achieve minimum on-voltage drop for low frequency applications (<1kHz). The built in collector-gate zener exhibits a very precise active clamping.

APPLICATIONS

- LIGHT DIMMER
- INRUSH CURRENT LIMITATION
- PRE-HEATING FOR ELECTRONIC LAMP BALLAST

Figure 1: Package

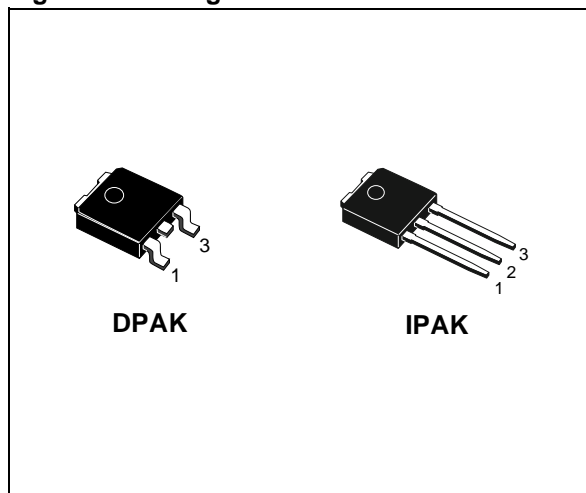


Figure 2: Internal Schematic Diagram

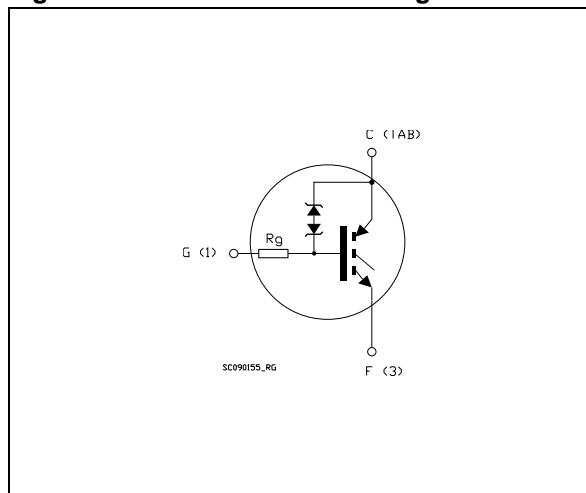


Table 2: Order Code

| PART NUMBER | MARKING | PACKAGE | PACKAGING |
|----------------|------------|---------|-------------|
| STGD5NB120SZT4 | GD5NB120SZ | DPAK | TAPE & REEL |
| STGD5NB120SZ-1 | GD5NB120SZ | IPAK | TUBE |

Table 3: Absolute Maximum ratings

| Symbol | Parameter | Value | Unit |
|--------------|---|------------|------|
| V_{CES} | Collector-Emitter Voltage ($V_{GS} = 0$) | 1200 | V |
| V_{ECR} | Emitter-Collector Voltage | 20 | V |
| V_{GE} | Gate-Emitter Voltage | ± 20 | V |
| I_C | Collector Current (continuous) at $T_C = 25^\circ\text{C}$ | 10 | A |
| I_C | Collector Current (continuous) at $T_C = 100^\circ\text{C}$ | 5 | A |
| I_{CM} (■) | Collector Current (pulsed) | 20 | A |
| P_{TOT} | Total Dissipation at $T_C = 25^\circ\text{C}$ | 55 | W |
| | Derating Factor | 0.44 | W/°C |
| Eas (1) | Single Pulse Avalanche Energy at $T_j = 25^\circ\text{C}$ | 10 | mJ |
| | Single Pulse Avalanche Energy at $T_j = 100^\circ\text{C}$ | 7 | mJ |
| T_{stg} | Storage Temperature | -55 to 150 | °C |
| T_j | Operating Junction Temperature range | 150 | °C |

(■) Pulse width limited by safe operating area

(1) $V_{CE} = 50\text{ V}$, $I_{AV} = 3.3\text{ A}$

Table 4: Thermal Data

| | | Min. | Typ. | Max. | |
|-----------|-------------------------------------|------|------|------|------|
| Rthj-case | Thermal Resistance Junction-case | | | 2.27 | °C/W |
| Rthj-amb | Thermal Resistance Junction-ambient | | | 100 | °C/W |

ELECTRICAL CHARACTERISTICS ($T_{CASE} = 25^\circ\text{C}$ UNLESS OTHERWISE SPECIFIED)
Table 5: On/Off

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------|---|--|------|------|-----------|--------------------------------|
| $V_{BR(CES)}$ | Collector-Emitter Breakdown Voltage | $I_C = 10\text{ mA}$, $V_{GE} = 0\text{ V}$ | 1200 | | | V |
| I_{CES} | Collector cut-off Current ($V_{GE} = 0$) | $V_{CE} = 900\text{ V}$ $V_{CE} = 900\text{ V}$, $T_j = 125^\circ\text{C}$ | | | 50 250 | μA μA |
| I_{GES} | Gate-Emitter Leakage Current ($V_{CE} = 0$) | $V_{GE} = \pm 20\text{ V}$, $V_{CE} = 0\text{ V}$ | | | ± 100 | nA |
| $V_{GE(th)}$ | Gate Threshold Voltage | $V_{CE} = V_{GE}$, $I_C = 250\text{ }\mu\text{A}$ | 2 | | 5 | V |
| V_{GE} | Gate Emitter Voltage | $V_{CE} = 2.5\text{ V}$, $I_C = 2\text{ A}$, $T_j = 25\div 125^\circ\text{C}$ | | | 6.5 | V |
| $V_{CE(sat)}$ | Collector-Emitter Saturation Voltage | $V_{GE} = 15\text{ V}$, $I_C = 5\text{ A}$ | | 1.3 | 2.0 | V |
| | | $V_{GE} = 15\text{ V}$, $I_C = 5\text{ A}$, $T_j = 125^\circ\text{C}$ | | 1.2 | | V |

ELECTRICAL CHARACTERISTICS (CONTINUED)

Table 6: Dynamic

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|-----------------|------------------------------|---|------|------|------|------------|
| g_{fs} | Forward Transconductance | $V_{CE} = 25\text{ V}$, $I_C = 5\text{ A}$ | | 5 | | S |
| $C_{ies}^{(*)}$ | Input Capacitance | $V_{CE} = 25\text{ V}$, $f = 1\text{ MHz}$, $V_{GE} = 0\text{ V}$ | | 430 | | pF |
| $C_{oes}^{(*)}$ | Output Capacitance | | | 40 | | pF |
| $C_{res}^{(*)}$ | Reverse Transfer Capacitance | | | 7 | | pF |
| R_g | Gate Resistance | | | 4 | | K Ω |

(1) Pulsed: Pulse duration= 300 μs , duty cycle 1.5%

Table 7: Switching On

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|----------------|-----------------------|---|------|------|------|------------------|
| $t_{d(on)}$ | Delay Time | $I_C = 5\text{ A}$, $V_{CC} = 960\text{ V}$ $V_{GE} = 15\text{ V}$, $R_{drive} = 1\text{ K}\Omega$ $T_j = 25^\circ\text{C}$ | | 690 | | ns |
| t_r | Current Rise Time | | | 170 | | ns |
| $(di/dt)_{on}$ | Turn-on Current Slope | | | 39.6 | | A/ μs |
| $t_{d(on)}$ | Dealy Time | $I_{CC} = 5\text{ A}$, $V_{CC} = 960\text{ V}$ $V_{GE} = 15\text{ V}$, $R_{drive} = 1\text{ K}\Omega$ $T_j = 125^\circ\text{C}$ | | 600 | | ns |
| t_r | Current Rise Time | | | 185 | | ns |
| $(di/dt)_{on}$ | Turn-on Current Slope | | | 39 | | A/ μs |

Table 8: Switching Off

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|----------------|-----------------------|--|------|------|------|---------------|
| t_c | Cross-over Time | $I_C = 5\text{ A}$, $V_{CC} = 960\text{ V}$ $V_{GE} = 15\text{ V}$, $R_{drive} = 1\text{ K}\Omega$ $T_j = 25^\circ\text{C}$ | | 4 | | μs |
| $t_r(V_{off})$ | Off Voltage Rise Time | | | 2.2 | | μs |
| $t_{d(off)}$ | Delay Time | | | 12.1 | | μs |
| t_f | Current Fall Time | | | 1.13 | | μs |
| t_c | Cross-over Time | $I_C = 5\text{ A}$, $V_{CC} = 960\text{ V}$ $V_{GE} = 15\text{ V}$, $R_{drive} = 1\text{ K}\Omega$ $T_j = 125^\circ\text{C}$ | | 5 | | μs |
| $t_r(V_{off})$ | Off Voltage Rise Time | | | 2.2 | | μs |
| $t_{d(off)}$ | Delay Time | | | 12.1 | | μs |
| t_f | Current Fall Time | | | 2 | | μs |

Table 9: Switching Energy

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max | Unit |
|--------------|--------------------------|--|------|-------|-----|------|
| $E_{on(2)}$ | Turn-on Switching Losses | $V_{CC} = 800\text{ V}$, $I_C = 3\text{ A}$ $R_G = 10\ \Omega$, $V_{GE} = 15\text{ V}$, $T_j = 25^\circ\text{C}$ (see Figure 18) | | 2.59 | | mJ |
| $E_{off(3)}$ | Turn-off Switching Loss | | | 9 | | mJ |
| E_{ts} | Total Switching Loss | | | 11.59 | | mJ |
| $E_{on(2)}$ | Turn-on Switching Losses | $V_{CC} = 800\text{ V}$, $I_C = 3\text{ A}$ $R_G = 10\ \Omega$, $V_{GE} = 15\text{ V}$, $T_j = 125^\circ\text{C}$ (see Figure 18) | | 2.64 | | mJ |
| $E_{off(3)}$ | Turn-off Switching Loss | | | 10.2 | | mJ |
| E_{ts} | Total Switching Loss | | | 12.68 | | mJ |

(2) E_{on} is the turn-on losses when a typical diode is used in the test circuit in figure 2.

(3) Turn-off losses include also the tail of the collector current.

Table 10: Functional Test

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max | Unit |
|-----------------|---------------------------------------|---|-------------|-------------|------------|-------------|
| I _{as} | Unclamped inductive switching current | V _{CC} = 50 V, L = 1.8 mH T _{start} = 25°C, R _{drive} = 1KΩ | 3.3 | | | A |
| I _{CL} | Latching Current | V _{CLAMP} = 960 V, T _j = 125°C R _{drive} = 1KΩ | | 10 | | A |

Figure 3: Output Characteristics

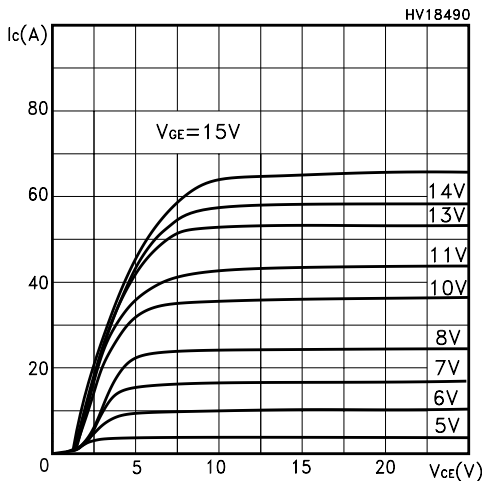


Figure 4: Transconductance

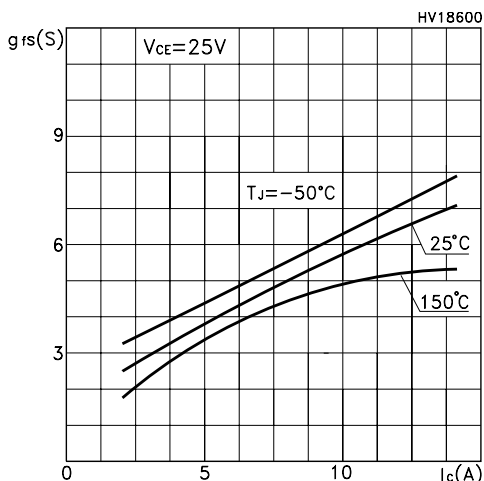


Figure 5: Collector-Emitter On Voltage vs Collector Current

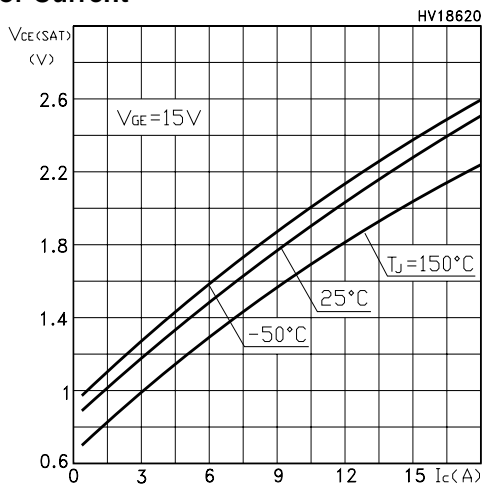


Figure 6: Transfer Characteristics

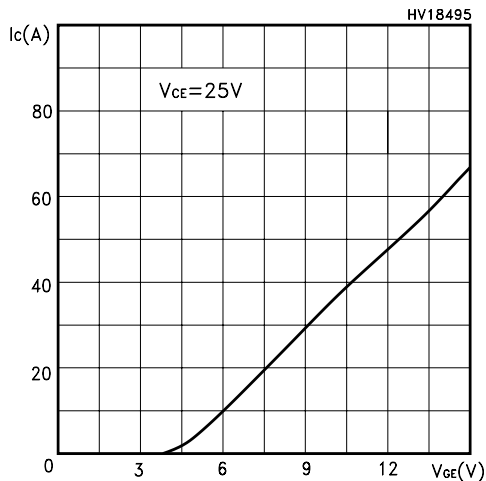


Figure 7: Collector-Emitter On Voltage vs Temperature

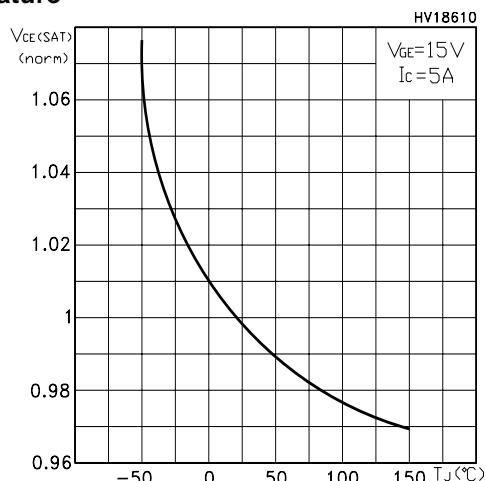


Figure 8: Normalized Gate Threshold vs Temperature

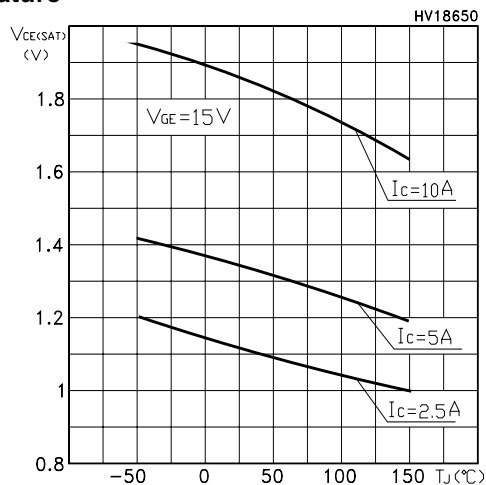


Figure 9: Gate Threshold vs Temperature

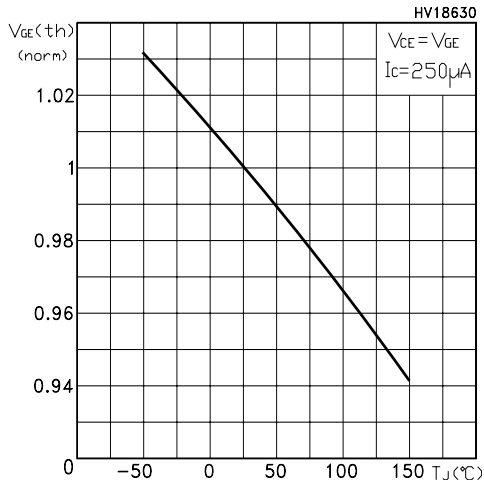


Figure 10: Capacitance Variations

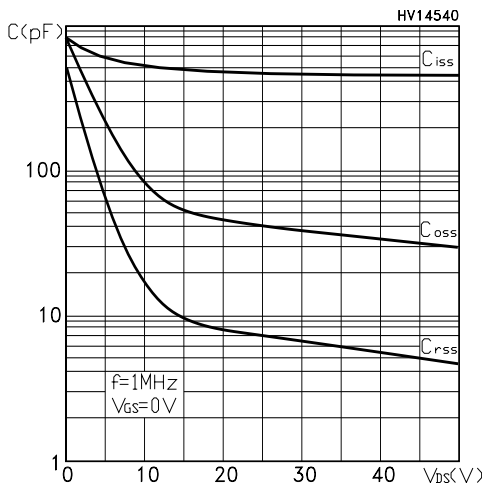


Figure 11: Switching Losses vs Gate Resistance

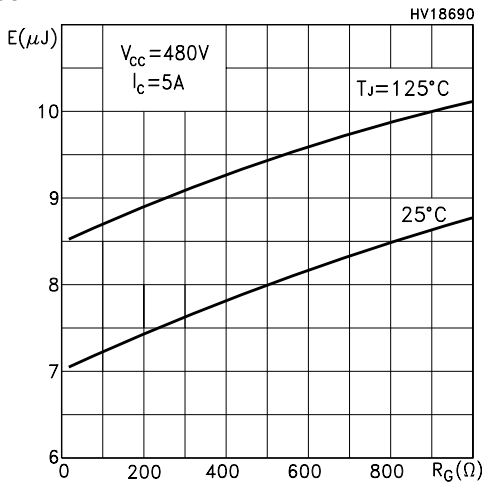


Figure 12: Breakdown Voltage vs Temperature

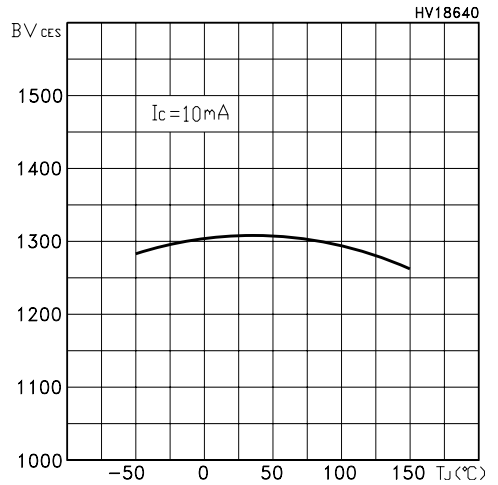


Figure 13: Gate-Charge vs Gate-Emitter Voltage

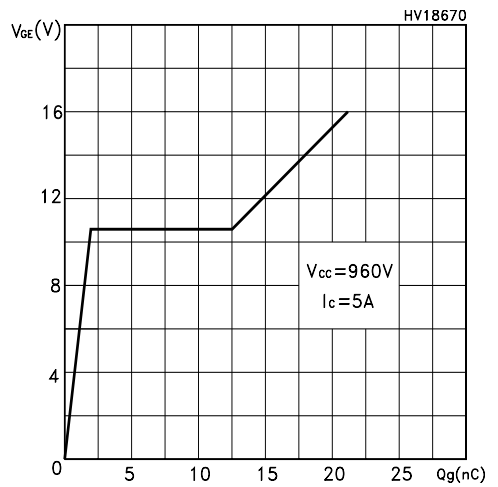


Figure 14: Switching Losses vs Collector Current

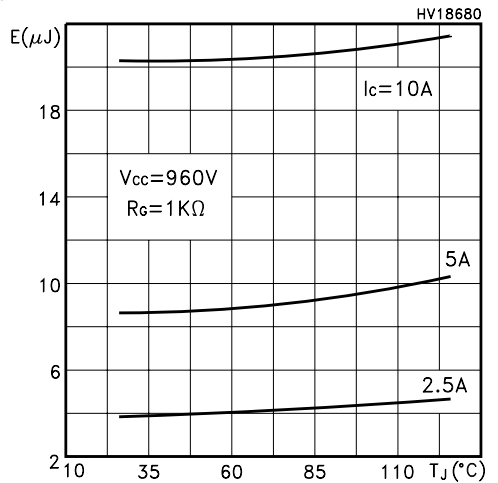


Figure 15: Thermal Impedance

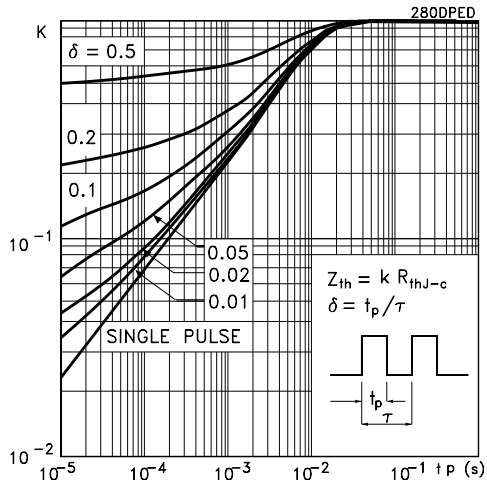


Figure 16: Turn-Off SOA

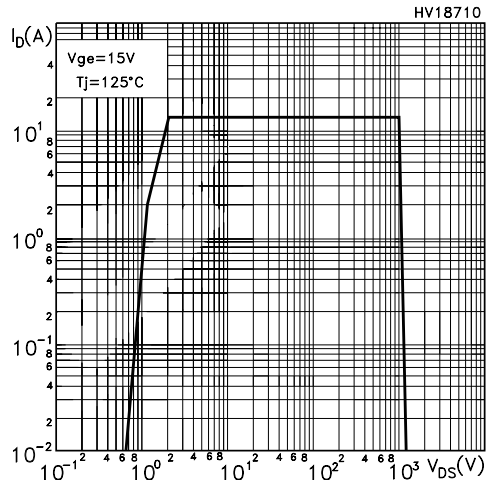


Figure 17: Test Circuit for Inductive Load Switching

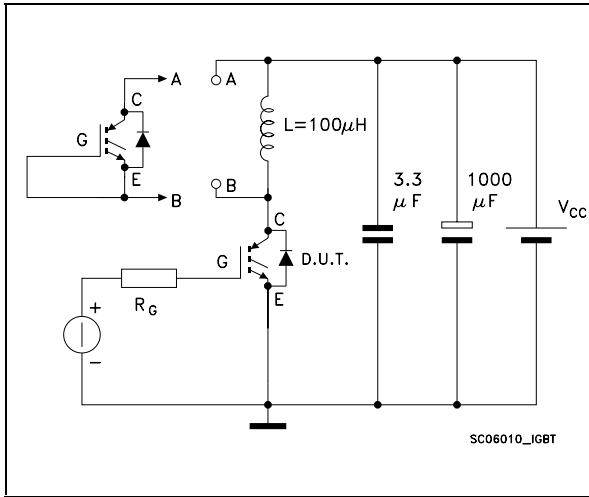


Figure 18: Switching Waveforms

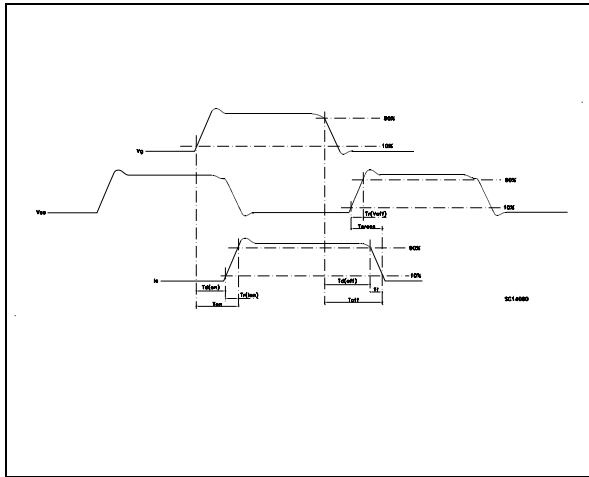


Figure 19: Gate Charge Test Circuit

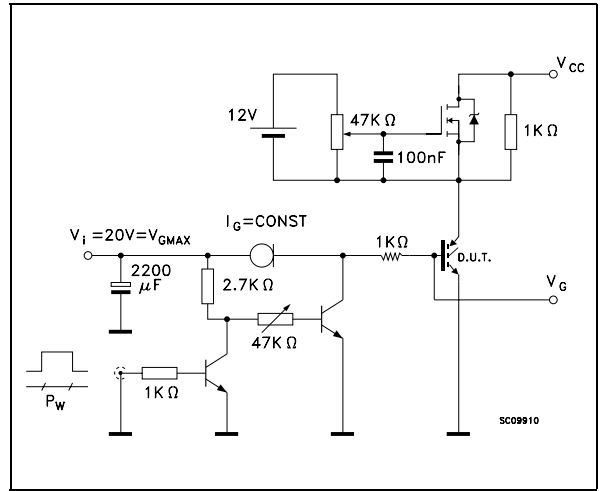
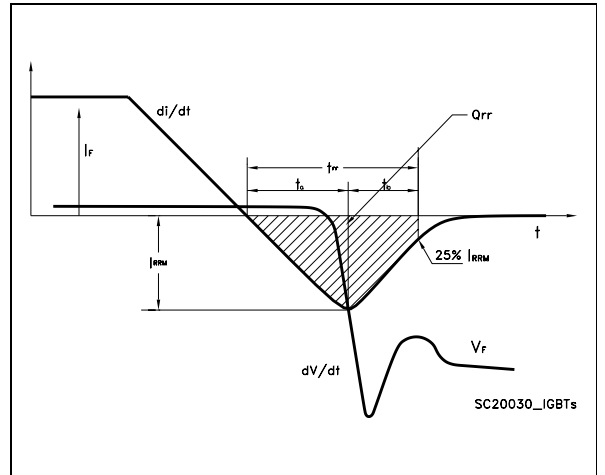
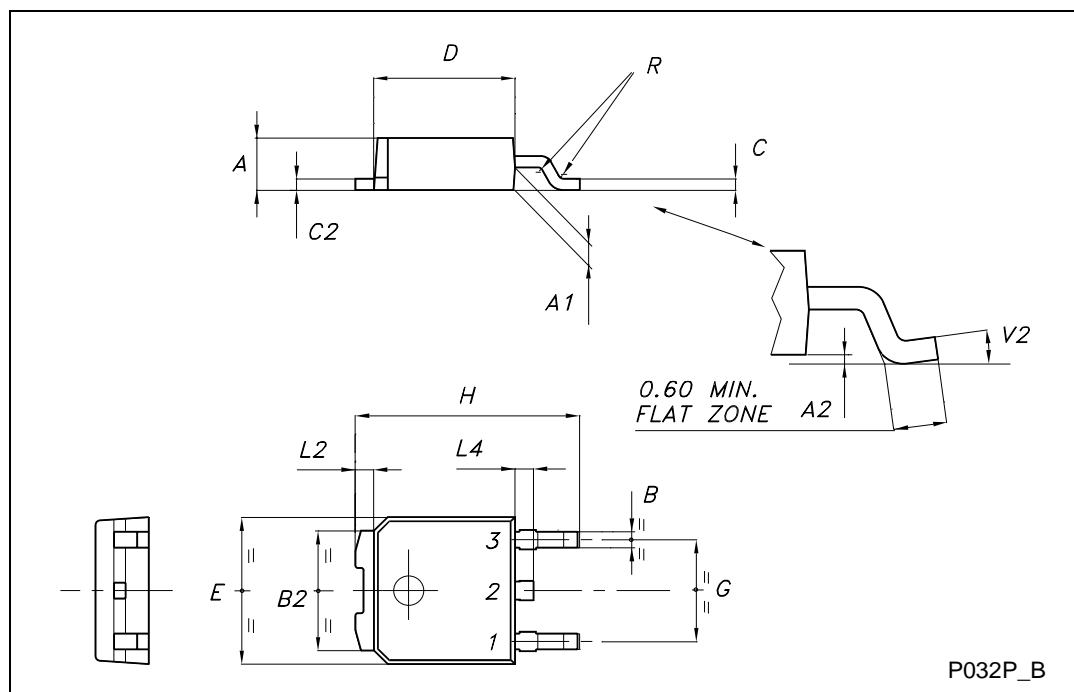


Figure 20: Diode Recovery Time Waveforms



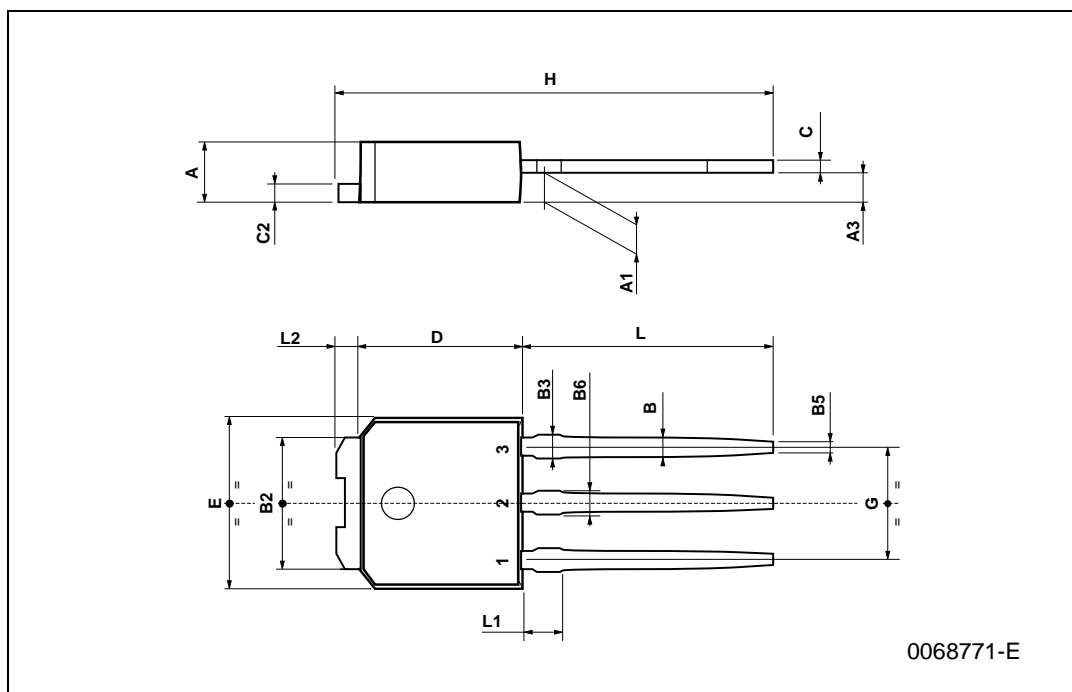
TO-252 (DPAK) MECHANICAL DATA

| DIM. | mm | | | inch | | |
|------|------|------|-------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 2.20 | | 2.40 | 0.087 | | 0.094 |
| A1 | 0.90 | | 1.10 | 0.035 | | 0.043 |
| A2 | 0.03 | | 0.23 | 0.001 | | 0.009 |
| B | 0.64 | | 0.90 | 0.025 | | 0.035 |
| B2 | 5.20 | | 5.40 | 0.204 | | 0.213 |
| C | 0.45 | | 0.60 | 0.018 | | 0.024 |
| C2 | 0.48 | | 0.60 | 0.019 | | 0.024 |
| D | 6.00 | | 6.20 | 0.236 | | 0.244 |
| E | 6.40 | | 6.60 | 0.252 | | 0.260 |
| G | 4.40 | | 4.60 | 0.173 | | 0.181 |
| H | 9.35 | | 10.10 | 0.368 | | 0.398 |
| L2 | | 0.8 | | | 0.031 | |
| L4 | 0.60 | | 1.00 | 0.024 | | 0.039 |
| V2 | 0° | | 8° | 0° | | 0° |

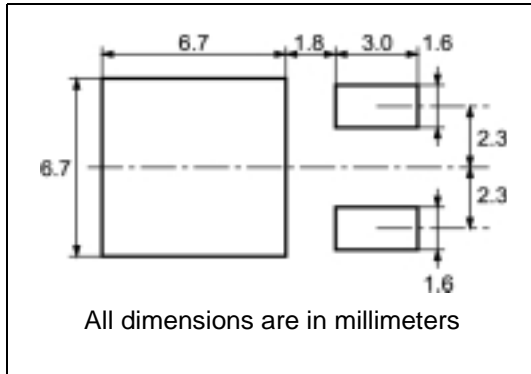


TO-251 (IPAK) MECHANICAL DATA

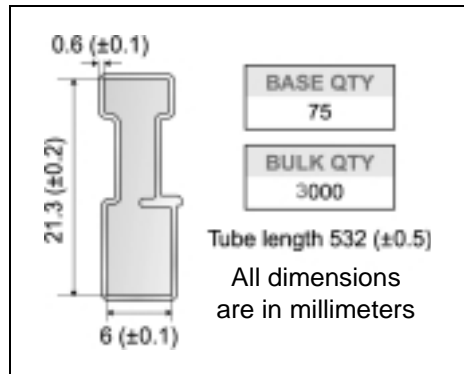
| DIM. | mm | | | inch | | |
|------|------|------|------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 2.2 | | 2.4 | 0.086 | | 0.094 |
| A1 | 0.9 | | 1.1 | 0.035 | | 0.043 |
| A3 | 0.7 | | 1.3 | 0.027 | | 0.051 |
| B | 0.64 | | 0.9 | 0.025 | | 0.031 |
| B2 | 5.2 | | 5.4 | 0.204 | | 0.212 |
| B3 | | | 0.85 | | | 0.033 |
| B5 | | 0.3 | | | 0.012 | |
| B6 | | | 0.95 | | | 0.037 |
| C | 0.45 | | 0.6 | 0.017 | | 0.023 |
| C2 | 0.48 | | 0.6 | 0.019 | | 0.023 |
| D | 6 | | 6.2 | 0.236 | | 0.244 |
| E | 6.4 | | 6.6 | 0.252 | | 0.260 |
| G | 4.4 | | 4.6 | 0.173 | | 0.181 |
| H | 15.9 | | 16.3 | 0.626 | | 0.641 |
| L | 9 | | 9.4 | 0.354 | | 0.370 |
| L1 | 0.8 | | 1.2 | 0.031 | | 0.047 |
| L2 | | 0.8 | 1 | | 0.031 | 0.039 |



DPAK FOOTPRINT



TUBE SHIPMENT (no suffix)*



TAPE AND REEL SHIPMENT (suffix "T4")*

40 mm min. Access hole at slot location

Full radius

Tape slot in core for tape start 2.5mm min. width

G measured at hub

REEL MECHANICAL DATA

| DIM. | mm | | inch | |
|------|------|------|-------|--------|
| | MIN. | MAX. | MIN. | MAX. |
| A | | 330 | | 12.992 |
| B | 1.5 | | 0.059 | |
| C | 12.8 | 13.2 | 0.504 | 0.520 |
| D | 20.2 | | 0.795 | |
| G | 16.4 | 18.4 | 0.645 | 0.724 |
| N | 50 | | 1.968 | |
| T | | 22.4 | | 0.881 |

| BASE QTY | BULK QTY |
|----------|----------|
| 2500 | 2500 |

TAPE MECHANICAL DATA

| DIM. | mm | | inch | |
|------|------|------|-------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A0 | 6.8 | 7 | 0.267 | 0.275 |
| B0 | 10.4 | 10.6 | 0.409 | 0.417 |
| B1 | | 12.1 | | 0.476 |
| D | 1.5 | 1.6 | 0.059 | 0.063 |
| D1 | 1.5 | | 0.059 | |
| E | 1.65 | 1.85 | 0.065 | 0.073 |
| F | 7.4 | 7.6 | 0.291 | 0.299 |
| K0 | 2.55 | 2.75 | 0.100 | 0.108 |
| P0 | 3.9 | 4.1 | 0.153 | 0.161 |
| P1 | 7.9 | 8.1 | 0.311 | 0.319 |
| P2 | 1.9 | 2.1 | 0.075 | 0.082 |
| R | 40 | | 1.574 | |
| W | 15.7 | 16.3 | 0.618 | 0.641 |

TOP COVER TAPE

10 pitches cumulative tolerance on tape +/- 0.2 mm

Center line of cavity

User Direction of Feed

FEED DIRECTION

Bending radius

* on sales type

Table 11: Revision History

| Date | Revision | Description of Changes |
|-------------|-----------------|-------------------------------|
| 06-Oct-2003 | 1 | First release |
| 18-Jan-2005 | 2 | Final datasheet |

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